



1. Four layer PCB, material FR-4, copper 1 oz, overall thickness 1.6 mm.
2. Layers structure:
  - Front copper
  - Prepreg 0.25 mm
  - Internal copper layer 1
  - Core 1 mm
  - Internal copper layer 2
  - Prepreg 0.25 mm
  - Bottom copper
3. Green solder mask on both sides.
4. White silkscreen on top layer.
5. Finish: HASL.

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Sheet:	SoilSensor.kicad_pcb
Title: Soil Moisture Sensor	
Size: A4	Date: 2020-02-25
KiCad E.D.A.	KiCad (5.1.4) - 1
Rev: 2.0	
Id: 1/1	